

Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
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EFS ID: 53686

Application ID: 10667227



Title of Invention: SEMICONDUCTOR PACKAGE AND  
METHOD OF MAKING USING  
LEADFRAME HAVING LEAD  
LOCKS TO SECURE LEADS TO  
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-18

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Submission Type: Information Disclosure  
Statement

Filing Type:

Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

Total Fees Authorized:


Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US

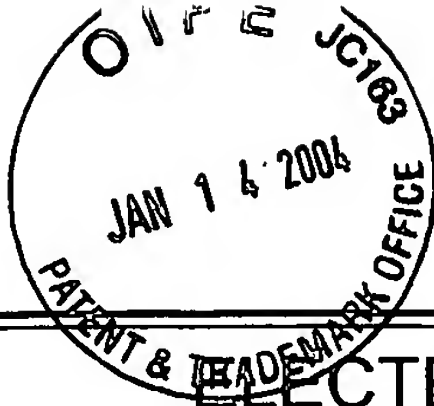
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# TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING USING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
Confirmation Number: 7012										
Attorney Docket Number: AMKOR012G1										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids1-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids1-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids1-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

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<div>Application Number: 10/667227</div> <div>Confirmation Number: 7012</div> <div>First Named Applicant: Jae Yee</div> <div>Attorney Docket Number: AMKOR012G1</div> <div>Art Unit: 2812</div> <div>Search string: ( 2596993 or 3435815 or 3734660 or 3838984 or 4054238 or 4189342 or 4258381 or 4289922 or 4301464 or 4332537 or 4417266 or 4451224 or 4530152 or 4541003 or 4646710 or 4707724 or 4727633 or 4737839 or 4756080 or 4812896 or 4862245 or 4862246 or 4907067 or 4920074 or 4935803 or 4942454 or 4987475 or 5018003 or 5029386 or 5041902 or 5057900 or 5059379 or 5065223 or 5070039 or 5087961 or 5091341 or 5096852 or 5118298 or 5151039 or 5157475 or 5157480 or 5168368 or 5172213 or 5172214 or 5175060 or 5200362 or 5200809 or 5214845 or 5216278 or 5218231 or 20010008305 or 20010014538 or 20010011654 or 20020024122 or 20020027297 or 20020140061 or 20020140068 or 20020163015 or 20030030131 or 20030073265 ).pn.</div> <div>US Patent Documents</div> <div>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</div> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>2596993</td><td>1952-05-20</td><td>S.L. GOOKIN</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>3435815</td><td>1969-04-01</td><td>FORCIER</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>3734660</td><td>1973-05-22</td><td>DAVIES ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>3838984</td><td>1974-10-01</td><td>CRANE ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>4054238</td><td>1977-10-18</td><td>LLOYD ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></tr></tbody></table>							init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	2596993	1952-05-20	S.L. GOOKIN					2	3435815	1969-04-01	FORCIER					3	3734660	1973-05-22	DAVIES ET AL.					4	3838984	1974-10-01	CRANE ET AL.					5	4054238	1977-10-18	LLOYD ET AL.											
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	6	4189342	1980-02-19	KOCK
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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	2	20010014538	2001-08-16	KWAN ET AL.			
	3	20010011654	2002-01-31	KIMURA			
	4	20020024122	2002-02-28	JUNG ET AL.			
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	6	20020140061	2002-10-03	LEE			
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	9	20030030131	2003-02-13	LEE ET AL.			
	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date